

## **Product Change Notification / GBNG-28BFRL552**

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02-Aug-2022

# **Product Category:**

Memory

# **PCN Type:**

Manufacturing Change

# **Notification Subject:**

eSign # E000123575 Final Notice: Qualification of UMC Fab 8D as an additional fabrication site for selected 24FC256, 24AA256 and 24LC256 device families available in 8L DFN-S (6x5x0.9mm), MSOP (3x3mm), PDIP (.300in), SOIC (3.90mm), SOIJ (.208in), TDFN (2x3x0.8mm), TSSOP (4.4mm) packages.

### **Affected CPNs:**

GBNG-28BFRL552\_Affected\_CPN\_08022022.pdf GBNG-28BFRL552\_Affected\_CPN\_08022022.csv

#### **Notification Text:**

**PCN Status:**Final Notification

PCN Type:Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of UMC Fab 8D as an additional fabrication site for selected 24FC256, 24AA256 and 24LC256 device families available in 8L DFN-S (6x5x0.9mm), MSOP (3x3mm), PDIP (.300in), SOIC (3.90mm), SOIJ (.208in), TDFN (2x3x0.8mm), TSSOP (4.4mm) packages.

#### **Pre and Post Change Summary:**

	Pre Cl	nange	Post Change				
Fabrication Site	Microchip Technology Tempe – Fab 2 (TMGR)  and  Microchip Technology Gresham – Fab 4 (GRTM)	Key Foundry Co., Ltd (MC04)	Microchip Technology Tempe – Fab 2 (TMGR)  and  Microchip Technology Gresham – Fab 4 (GRTM)	Key Foundry Co., Ltd (MC04)	United Microelectronics Corporation (Fab 8D) (U08D)		
Wafer	8 inches (200	8 inches (200	8 inches (200	8 inches (200	8 inches (200		
Diameter	mm)	mm)	mm)	mm)	mm)		
Certifications	ISO/TS16949	ISO/TS16949	ISO/TS16949	ISO/TS16949	ISO/TS16949		

# Impacts to Data Sheet:None

## Change ImpactNone

**Reason for Change:**To improve manufacturability by qualifying UMC Fab 8D as an additional fabrication site.

# **Change Implementation Status:**In Progress

Estimated First Ship Date:September 19, 2022 (date code: 2239)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

## **Time Table Summary:**

	August 2022				September 2022				
Workweek	3 2	3	3 4	3 5	3 6	3	3 8	3 9	4
		<u>ა</u>	4	3	0		0	9	U
Qual Report Availability	Х								
Final PCN Issue	Х								
Date		*							
Estimated									
Implementation								Х	
Date									

Method to Identify Change:Traceability Code

Qualification Report:Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**August 02, 2022: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

#### **Attachments:**

PCN\_GBNG-28BFRL552\_Qual\_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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#### Affected Catalog Part Numbers (CPN)

24LC256-E/MS

24AA256-E/MS

24LC256-E/MF

24AA256-E/MF

24LC256-E/SN

24AA256-E/SN

24FC256-E/SN

24LC256-E/SM

24AA256-E/SM

24LC256-E/P

24AA256-E/P

24LC256-E/ST

24AA256-E/ST

24FC256-E/ST

24LC256-I/MS

24AA256-I/MS

24FC256-I/MS

24LC256-I/MF

24AA256-I/MF

24FC256-I/MF

24LC256-I/SN

24AA256-I/SN

24FC256-I/SN

24LC256-I/SM

24AA256-I/SM

24FC256-I/SM

24LC256-I/P

24AA256-I/P

24FC256-I/P

24LC256-I/ST

24AA256-I/ST

24FC256-I/ST

24LC256T-I/MS

24AA256T-I/MS

24FC256T-I/MS

24LC256T-I/MF

24AA256T-I/MF

24FC256T-I/MF 24LC256T-I/SN

24AA256T-I/SN

24FC256T-I/SN

24LC256T-I/SM

24AA256T-I/SM

24FC256T-I/SM

24LC256T-I/ST

24AA256T-I/ST

Date: Tuesday, August 02, 2022

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24FC2561-I/S1

24LC256T-E/MS

24AA256T-E/MS

24AA256T-E/MF

24LC256T-E/SN

24AA256T-E/SN

24FC256T-E/SN

24LC256T-E/SM

24AA256T-E/SM

24LC256T-E/ST

24AA256T-E/ST

24FC256T-E/ST

24LC256T-I/MNY

24AA256T-I/MNY

24FC256T-I/MNY

24LC256T-E/MNY

24AA256T-E/MNY

Date: Tuesday, August 02, 2022